ASSIGNMENT RECC 102037325 To: Honorable Commi ssioner of Patents and Trademark Please record the attached original document or copy thereof. 1. Name of conveying parties: Jin shown Shie a) c) Chien chen Hung b) Chih yuan Yen d) Mei hsueh Peng 2. Name and address of receiving party: Name: a) Opto Tech Corporation Address: No. 8, Innovation Rd. 1, Hsinchu Science-Based **Industrial Park** Hsinchu, Taiwan, R.O.C. 3. Nature of conveyance Assignment Merger Security Agreement Change of Name License Agreement Other Execution Dates: February 4, 2002, February 4, 2002, February 7, 2002 and February 7, 2002, respectively. Application Number(s) or Patent Number(s): Not yet assigned 4. The title of the new application is: HEAT DISSIPATION STRUCTURE FOR SOLID-STATE LIGHT EMITTING DEVICE PACKAGE Please send all correspondence concerning this document to: 5. Albert S. Penilla 3/25/2002 RHARISI 00000017 10102131 MARTINE & PENILLA, LLP 710 Lakeway Drive, Suite 170 40.00 OP Sunnyvale, CA 94085 **Customer Number 25920** Tel. No. (408) 749-6900 Fax No.: (408) 749-6901 Total number of applications and patents involved: 1 6. Total fee (37 CFR 3.41): \$40.00 7. Enclosed Authorized to be charged to Deposit Account No. 50-0805 (Order No. JLINP080) To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. 8. Date: March 19, 2002 Albert S. Penilla, Esq. Registration No. 39,487

(Revised 01/96)

02 FC:581

ASSIGNMENT OF PATENT APPLICATION

Q0969

For good and valuable consideration, receipt of which hereby acknowledged,

I/We,

- (a) Jin-shown SHIE
- (b) Chih-yuan YEN
- (c) Chien-chen HUNG
- (d) Mei-hsueh PENG

residing at

- (a) 3F, No. 212, Ta Hsueh Road, Hsin Chu, Taiwan, R.O.C.
- (b) No. 1, Lihsin Rd. 5, Hsinchu Science-Based Industrial Park, HsinChu, Taiwan, R.O.C.
- (c) No. 1, Lihsin Rd. 5, Hsinchu Science-Based Industrial Park, HsinChu, Taiwan, R.O.C.
- (d) No. 1, Lihsin Rd. 5, Hsinchu Science-Based Industrial Park, HsinChu, Taiwan, R.O.C.

assign and transfer to: OPTO TECH CORPORATION

a corporation organized under the law of Taiwan and having a place of business at :

No. 8, Innovation Road 1, SBIP, Hsin Chu, Taiwan, R.O.C.

its successors and assigns, my entire right, title and interest, including the right of priority, in, to and under an application for Letters Patent of the United States entitled:

HEAT DISSIPATION STRUCTURE FOR SOLID-STATE LIGHT EMITTING DEVICE PACKAGE

including divisions, reissues, continuations and extensions thereof, and all rights of priority without further authorization from me; I agree to execute all papers useful in connection with said United States application, and generally to do everything possible to aid said assignee, its successors, assigns and nominees, at their request and expense, in obtaining and enforcing patents for said invention in United States; and I request the Commissioner of Patents and Trademarks to issue all patents granted for said invention to the above-named assignee, its successors and assigns.

Joint Inventor (a)	Jin-shown SHIE		
Inventor's	3/20201	Date	Feb 4 2002
Signature	III in Chu	Citizenship	Taiwan, R.O.C.
Residence	HsinChu		

PATENT REEL: 012718 FRAME: 0187

Joint Inventor (b)	Chih-yuan YEN		
Inventor's Signature	Chih Yum Yen	Date	2002/2/4
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Joint Inventor (c)	Chien-chen HUNG		
Inventor's Signature	Collen-Church Humz	Date	2007/2/1
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Joint Inventor (d)	Mei-hsueh PENG		
Inventor's Signature	Allie Cult Fing	Date	Feb 7,2002
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PATENT REEL: 012718 FRAME: 0188

RECORDED: 03/19/2002